

# 2SD2051

## Silicon NPN epitaxial planar type Darlington

For low-frequency amplification

### Features

- High forward current transfer ratio  $h_{FE}$
- Incorporating a built-in zener diode
- Full-pack package which can be installed to the heat sink with one screw

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ )

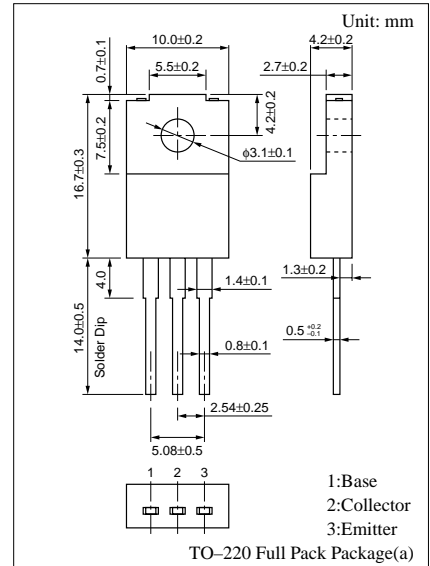
Parameter	Symbol	Ratings	Unit	
Collector to base voltage	$V_{CBO}$	$60\pm 10$	V	
Collector to emitter voltage	$V_{CEO}$	$60\pm 10$	V	
Emitter to base voltage	$V_{EBO}$	5	V	
Peak collector current	$I_{CP}$	2.5	A	
Collector current	$I_C$	1.6	A	
Collector power dissipation	$P_C$	$T_C=25^\circ\text{C}$	12	W
		$T_a=25^\circ\text{C}$	2.0	
Junction temperature	$T_j$	150	$^\circ\text{C}$	
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$	

### Electrical Characteristics ( $T_C=25^\circ\text{C}$ )

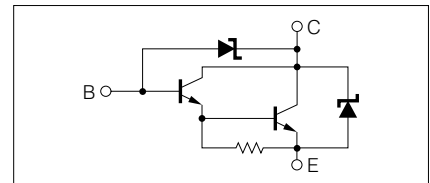
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 25\text{V}, I_E = 0$			1	$\mu\text{A}$
Emitter cutoff current	$I_{EBO}$	$V_{EB} = 4\text{V}, I_C = 0$			1	$\mu\text{A}$
Collector to base voltage	$V_{CBO}$	$I_C = 100\mu\text{A}, I_E = 0$	50		70	V
Collector to emitter voltage	$V_{CEO}$	$I_C = 1\text{mA}, I_B = 0$	50		70	V
Emitter to base voltage	$V_{EBO}$	$I_E = 100\mu\text{A}, I_C = 0$	5			V
Forward current transfer ratio	$h_{FE}^*$	$V_{CE} = 10\text{V}, I_C = 1.0\text{A}$	4000		40000	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 1.0\text{A}, I_B = 1.0\text{mA}$			1.5	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = 1.0\text{A}, I_B = 1.0\text{mA}$			2.2	V
Transition frequency	$f_T$	$V_{CE} = 10\text{V}, I_C = 10\text{mA}, f = 200\text{MHz}$	200			MHz

\* $h_{FE}$  Rank classification

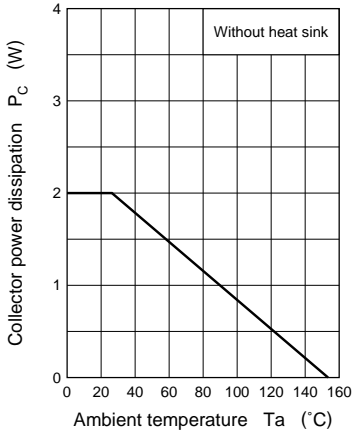
Rank	Q	R	S
$h_{FE}$	4000 to 10000	8000 to 20000	16000 to 40000



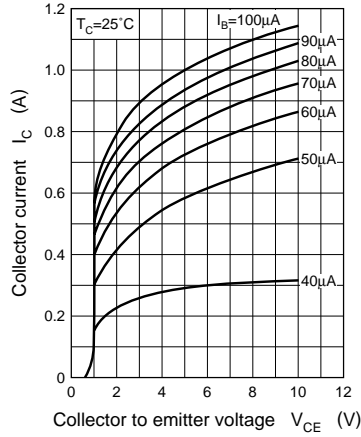
### Internal Connection



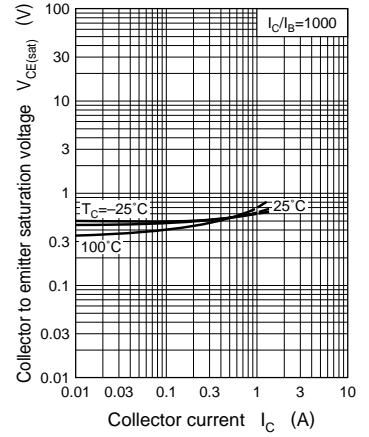
$P_C - T_a$



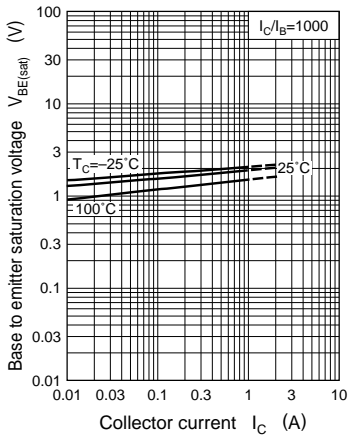
$I_C - V_{CE}$



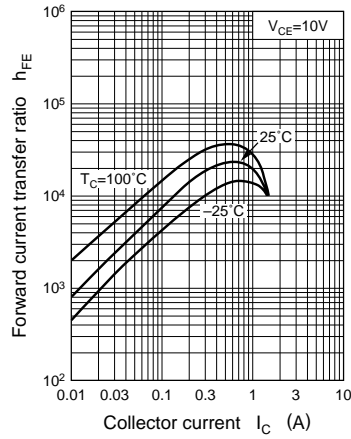
$V_{CE(sat)} - I_C$



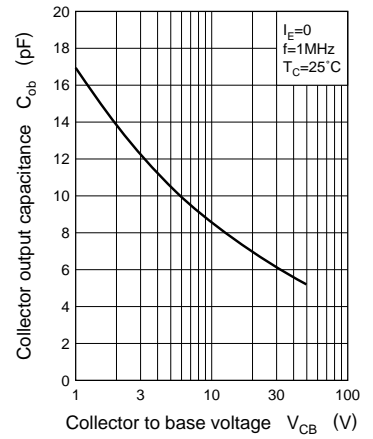
$V_{BE(sat)} - I_C$



$h_{FE} - I_C$



$C_{ob} - V_{CB}$



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